# 目录

电性参数

[redacted]

可靠性实验

[redacted]

包装

[redacted]

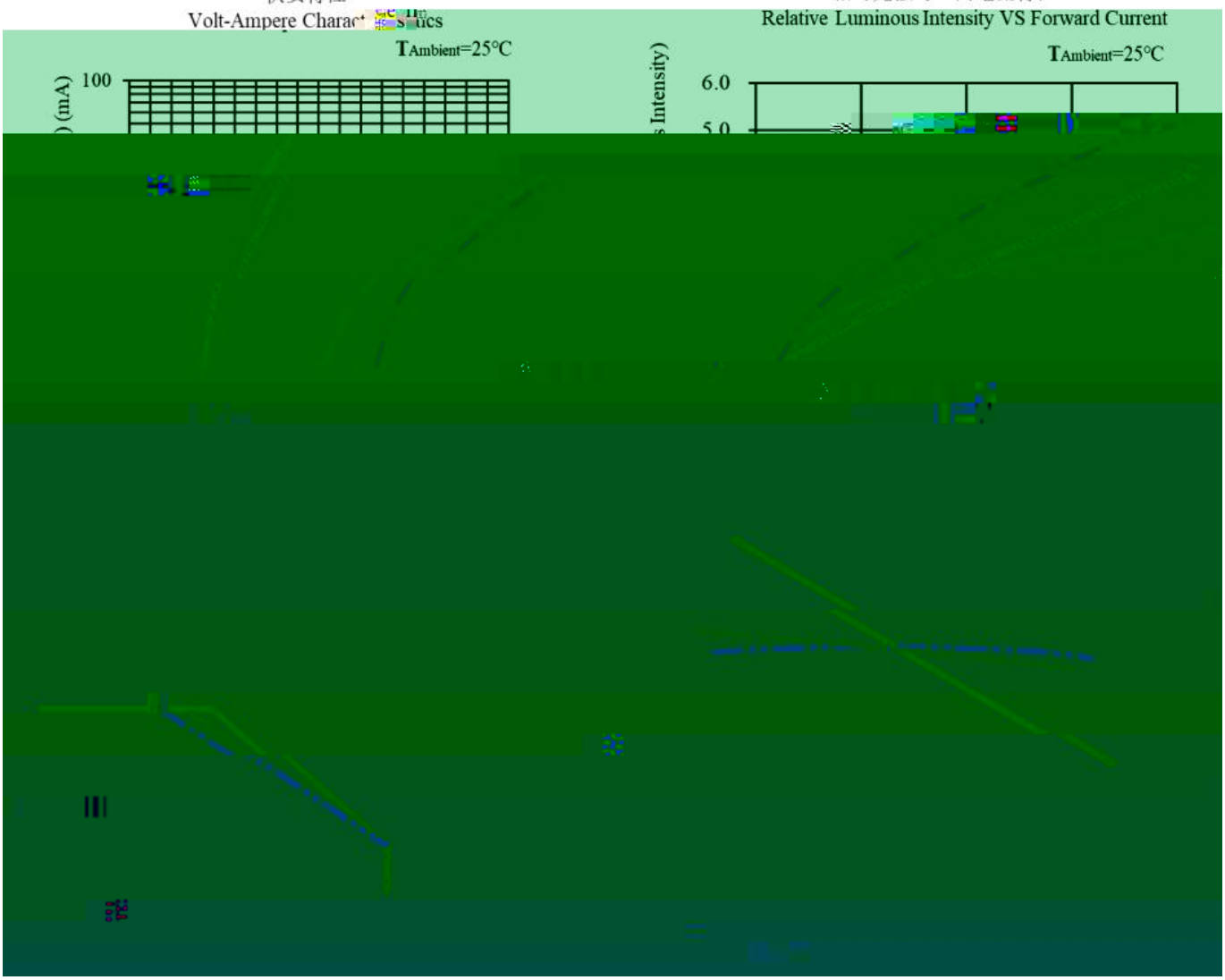
[redacted]

# 典型特性曲线

## Typical Characteristics Curves

伏安特性

Volt-Ampere Characteristics



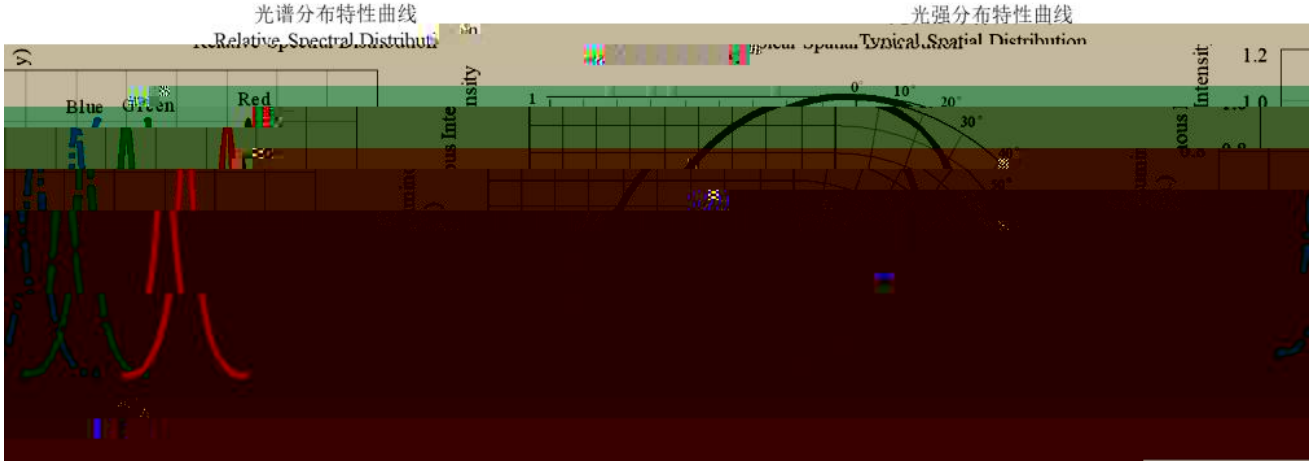

相对光强与正向电流特性

Relative Luminous Intensity VS Forward Current



光谱分布特性曲线

Relative Spectral Distribution



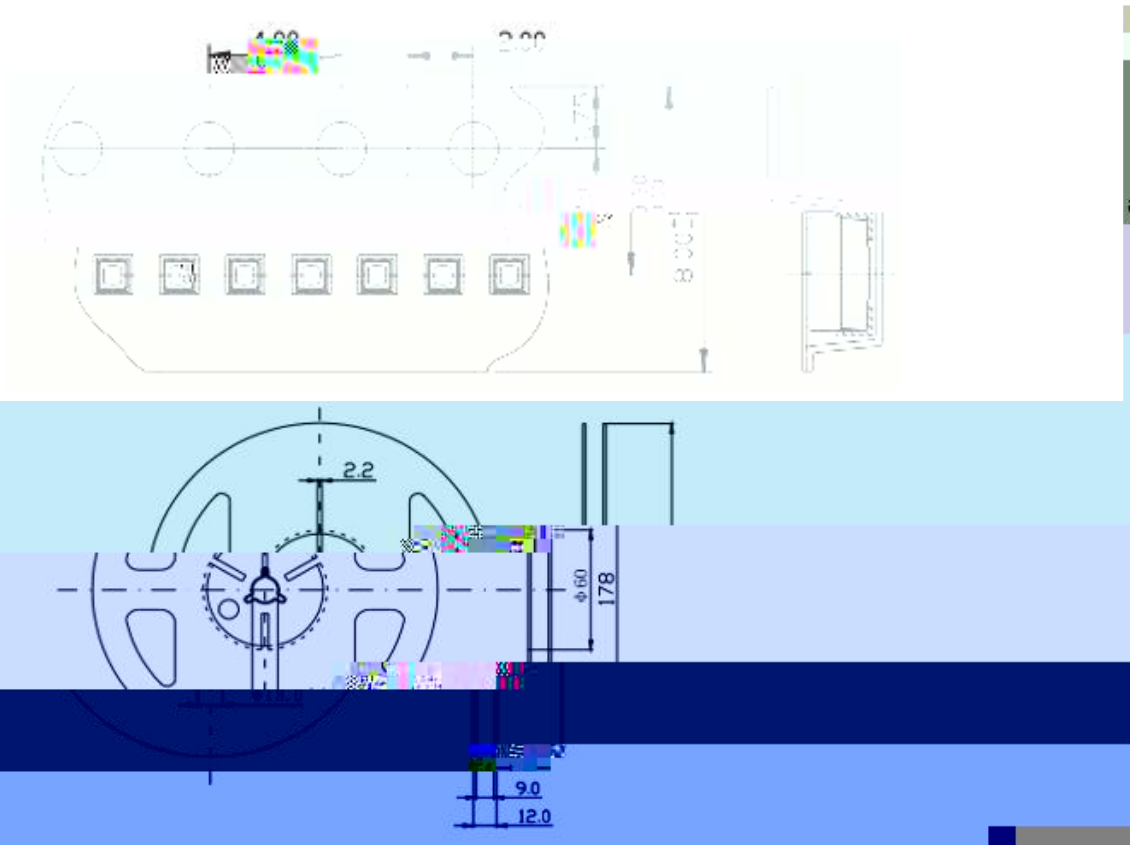

光强分布特性曲线

Typical Spatial Distribution

# 包装（1）

## Packaging (1)

载带与圆盘尺寸

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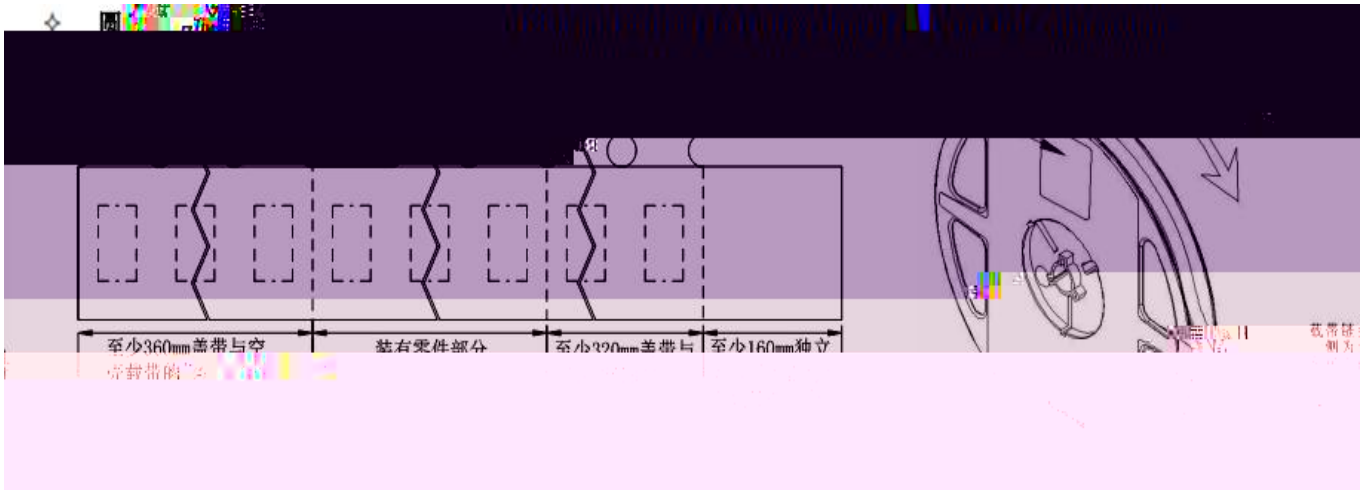
1. (mm)

1. Size unit is mm (mm).

2. ±0.1mm

2. The dimensional tolerance is ± 0.1mm.



Guideline for

30W

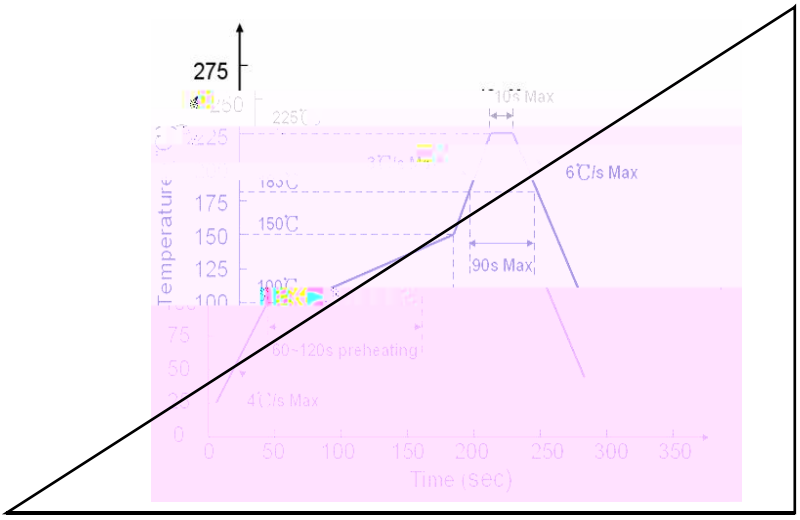
300 3

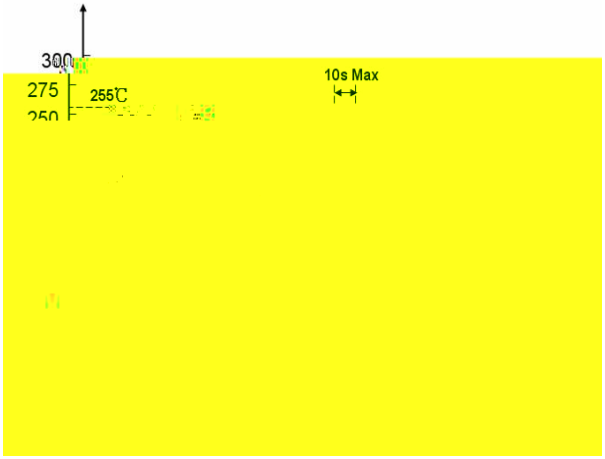
LED

Manual soldering is recommended only for repair and heavy industry situations. A soldering iron of less than 30W is recommended to be used in Hand Soldering. Please keep the temperature of the soldering iron under 300 while soldering. Each terminal of the LED is to go for less than 3 second and for one time only.

Be careful because the damage of the product is often started at the time of the hand soldering.

bedering. Use the conditions shown in the figure below for Reflow Soldering.



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Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to a minimum.

. 30 60%RH

Before opening the package, the product should be kept at 30 or less and humidity less than 60% RH, and be used within a year.

. 30 10%RH 168 7

30 ∓60%RH

After opening the package, the product should be stored at 30 or less and humidity less than 60%RH, and be soldered within 168 hours (7 days). It is recommended that the product be operated at the workshop condition of 30 or less and humidity less than 60%RH.

. LED

60 ± 5 24

If the moisture absorbent material has fade away or the LEDs have exceeded the storage time, baking treatment should be performed based on the following condition: (60 ± 5) for 24 hours.

**静电：**

Static electricity or surge